

# Product Change Notification - JAON-06LEME647

#### Date:

08 Aug 2018

#### **Product Category:**

32-bit Microcontrollers

#### Affected CPNs:

#### 7

### Notification subject:

CCB 3497 Initial Notice: Qualification of MMT as an additional assembly site for selected Atmel products of 58.85K wafer technology available in 100L TQFP (14x14x1.0mm) package.

### Notification text:

### **PCN Status:**

Initial notification

### PCN Type:

Manufacturing Change

## **Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

## **Description of Change:**

Qualification of MMT as an additional assembly site for selected Atmel products of 58.85K wafer technology available in 100L TQFP (14x14x1.0mm) package.

### Pre Change:

Assembled at ANAP using AuPd or PdCu wire, 3230 die attach, G700 mold compound and C194 leadframe material or assembled at ASE using PdCu or CuPdAu wire, CRM-1076WA die attach, EME-G631H mold compound and C7025 leadframe material.

#### **Post Change:**

Assembled at ANAP using AuPd or PdCu wire, 3230 die attach, G700 mold compound and C194 leadframe material or assembled at ASE using PdCu or CuPdAu wire, CRM-1076WA die attach, EME-G631H mold compound and C7025 leadframe material or assembled at MMT using Au wire, 3280 die attach, G700 mold compound and C7025 leadframe material.

	Pre C	hange	Post Change				
Assembly Site	Amkor Technology Philippine (P1/P2), INC. (ANAP)	ASE Inc. Taiwan (ASE)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	ASE Inc. Taiwan (ASE)	Microchip Technology Thailand Branch (MMT)		
Wire material	AuPd/PdCu	PdCu/CuPdAu	AuPd/PdCu	PdCu/CuPdAu	Au		
Die attach material	3230	CRM-1076WA	3230	CRM-1076WA	3280		
Molding compound material	G700	EME-G631H	G700	EME-G631H	G700		
Lead frame material	C194	C7025	C194	C7025	C7025		
MSL Classification	MSL 3	MSL 3	MSL 3	MSL 3	MSL 1 or MSL 2		

## Pre and Post Change Summary:



#### Impacts to Data Sheet:

None

Change Impact:

None

**Reason for Change:** 

To improve on-time delivery performance by qualifying MMT as an additional new assembly site.

Change Implementation Status:

In Progress

## **Estimated Qualification Completion Date:**

November 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

## Time Table Summary:

	August 2018				>	November 2018				
Workweek	31	32	33	34	35	>	45	46	47	48
Initial PCN Issue Date		Х								
Qual Report Availability								Х		
Final PCN Issue Date								Х		

## Method to Identify Change:

Traceability code

## Qualification Plan:

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan.

#### **Revision History:**

August 8, 2018: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

#### Attachment(s):

PCN\_JAON-06LEME647\_Qual\_Plan.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

## **Terms and Conditions:**

If you wish to change your product/process change notification (PCN) profile please log on to our website at <a href="http://www.microchip.com/PCN">http://www.microchip.com/PCN</a> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to <u>microchipDIRECT</u> and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

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Affected Catalog Part Numbers (CPN)

AT32UC3A1128-AUR AT32UC3A1128-AUT AT32UC3A1256-AUR AT32UC3A1256-AUT AT32UC3A1512-AUR AT32UC3A1512-AUT AT32UC3C1128C-AUR AT32UC3C1128C-AUT AT32UC3C1256C-AUR AT32UC3C1256C-AURA0 AT32UC3C1256C-AUT AT32UC3C1512C-AUR AT32UC3C1512C-AUT AT32UC3C164C-AUR AT32UC3C164C-AUT ATSAM4LC2CA-AU ATSAM4LC2CA-AUR ATSAM4LC4CA-AU ATSAM4LC4CA-AUR ATSAM4LC8CA-AU ATSAM4LC8CA-AUR ATSAM4LS2CA-AU ATSAM4LS2CA-AUR ATSAM4LS4CA-AU ATSAM4LS4CA-AUR ATSAM4LS8CA-AU ATSAM4LS8CA-AUR